

NDC651N

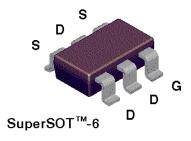
N-Channel Logic Level Enhancement Mode Field Effect Transistor

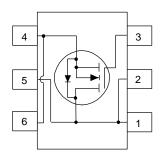
General Description

These N-Channel logic level enhancement mode power field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. This very high density process is tailored to minimize on-state resistance. These devices are particularly suited for low voltage applications in notebook computers, portable phones, PCMICA cards, and other battery powered circuits where fast switching, and low in-line power loss are needed in a very small outline surface mount package.

Features

- Proprietary SuperSOTTM-6 package design using copper lead frame for superior thermal and electrical capabilities.
- High density cell design for extremely low R_{DS(ON)}.
- Exceptional on-resistance and maximum DC current capability.





Absolute Maximum Ratings T_A = 25°C unless otherwise note

Symbol	Parameter		NDC651N	Units
/ _{DSS}	Drain-Source Voltage		30	V
/ _{GSS}	Gate-Source Voltage - Continuous		20	V
)	Drain Current - Continuous	(Note 1a)	3.2	A
- Pulsed			15	
P_{D}	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	1	
		(Note 1c)	0.8	
J,T _{STG}	Operating and Storage Temperature Range		-55 to 150	°C
HERMA	AL CHARACTERISTICS	•		·
R _{OJA}	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
R _{BJC}	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

Symbol	Parameter	Conditions		Min	Тур	Max	Units
OFF CHA	ARACTERISTICS			•	•		
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		30			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24 \text{ V}, \ V_{GS} = 0 \text{ V}$				1	μΑ
			$T_J = 55^{\circ}C$			10	μΑ
I _{GSSF}	Gate - Body Leakage, Forward	$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$				100	nA
I _{GSSR}	Gate - Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$				-100	nA
ON CHAI	RACTERISTICS (Note 2)			•	•		
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		1	1.7	3	V
			$T_{J} = 125^{\circ}C$	0.7	1.3	2.2	
R _{DS(ON)}	Static Drain-Source On-Resistance	$V_{GS} = 4.5 \text{ V}, \ I_{D} = 3.2 \text{ A}$	•		0.068	0.09	Ω
			$T_{J} = 125^{\circ}C$		0.095	0.18	
		$V_{GS} = 10 \text{ V}, I_{D} = 4 \text{ A}$	•		0.042	0.06	
I _{D(on)}	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$		10			Α
g _{FS}	Forward Transconductance	$V_{DS} = 10 \text{ V}, I_{D} = 3.2 \text{ A}$			6		S
DYNAMIC	CHARACTERISTICS						
C _{iss}	Input Capacitance	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$			290		pF
C _{oss}	Output Capacitance				180		pF
C _{rss}	Reverse Transfer Capacitance				60		pF
SWITCHI	NG CHARACTERISTICS (Note 2)						
t _{D(on)}	Turn - On Delay Time	$V_{DD} = 10 \text{ V}, \ I_{D} = 1 \text{ A},$ $V_{GEN} = 4.5 \text{ V}, R_{GEN} = 6 \Omega$			9	20	ns
t,	Turn - On Rise Time				19	30	ns
$\mathbf{t}_{D(off)}$	Turn - Off Delay Time				15	30	ns
t,	Turn - Off Fall Time				7	20	ns
Q_g	Total Gate Charge	$V_{DS} = 15 \text{ V},$ $I_{D} = 3.2 \text{ A}, V_{GS} = 10 \text{ V}$			10	20	nC
Q_{gs}	Gate-Source Charge				1.2		nC
Q_{gd}	Gate-Drain Charge				2.6		nC

ELECTRICAL CHARACTERISTICS (T _A = 25°C unless otherwise noted)							
Symbol	Parameter Conditions		Min	Тур	Max	Units	
DRAIN-SOURCE DIODE CHARACTERISTICS							
Is	Continuous Source Diode Current				1.3	Α	
V _{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 1.3 \text{ A (Note 2)}$		8.0	1.2	V	

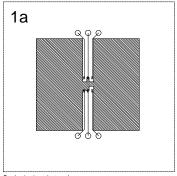
Notes:

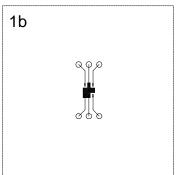
1. R_{BJA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{BJC} is guaranteed by design while R_{BCA} is determined by the user's board design.

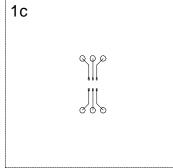
$$P_D(t) = \frac{T_J \cdot T_A}{R_{\theta J} \cdot \hat{k}^t} = \frac{T_J \cdot T_A}{R_{\theta J} \cdot \hat{t}^t R_{\theta C} \hat{k}^t} = I_D^2(t) \times R_{DS(QN)} \cdot \hat{\theta}_{TJ}$$

Typical $R_{\rm g,A}$ using the board layouts shown below on 4.5"x5" FR-4 PCB in a still air environment:

- a. 78°C/W when mounted on a 1 in² pad of 2oz cpper.
- b. 125°C/W when mounted on a 0.01 in² pad of 2oz cpper.
- c. 156°C/W when mounted on a 0.003 in² pad of 2oz cpper.







Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width $\leq 300 \mu s,$ Duty Cycle $\leq 2.0 \%.$

Typical Electrical Characteristics

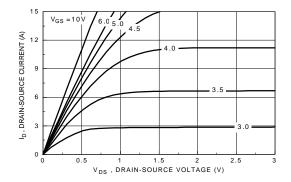


Figure 1. On-Region Characteristics

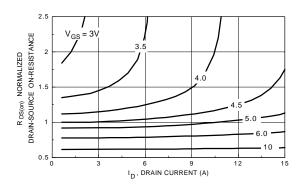


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

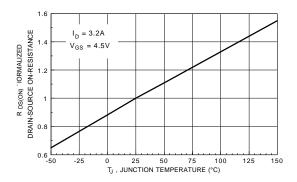


Figure 3. On-Resistance Variation with Temperature

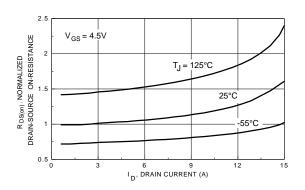


Figure 4. On-Resistance Variation with Drain Current and Temperature

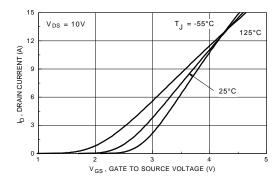


Figure 5. Transfer Characteristics

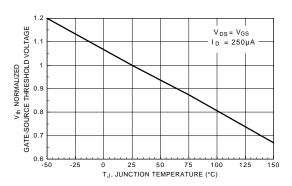


Figure 6. Gate Threshold Variation with Temperature

Typical Electrical Characteristics (continued)

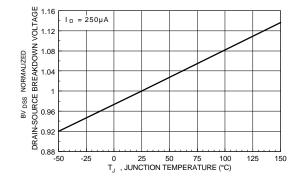


Figure 7. Breakdown Voltage Variation with Temperature

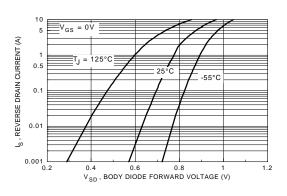


Figure 8. Body Diode Forward Voltage Variation with Source Current and Temperature

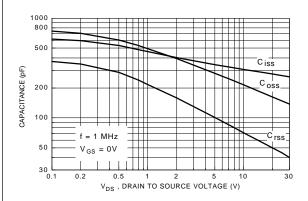


Figure 9. Capacitance Characteristics

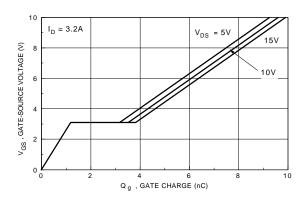


Figure 10. Gate Charge Characteristics

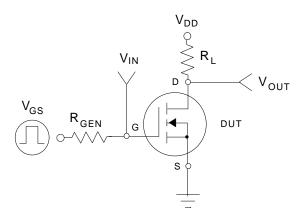


Figure 11. Switching Test Circuit

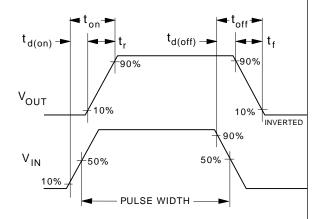
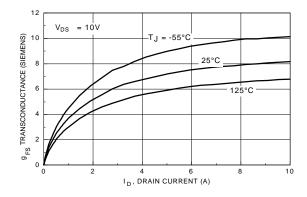


Figure 12. Switching Waveforms

Typical Electrical and Thermal Characteristics (continued)



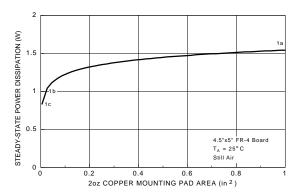
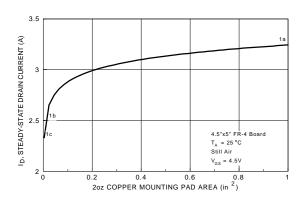


Figure 13. Transconductance Variation with Drain Current and Temperature

Figure 14. SOT-6 Maximum Steady-State Power Dissipation versus Copper Mounting Pad Area.



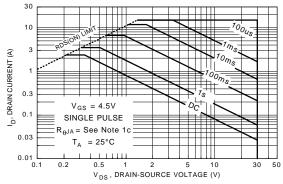


Figure 15. Maximum Steady-State Drain Current versus Copper Mounting Pad Area.

Figure 16. Maximum Safe Operating Area

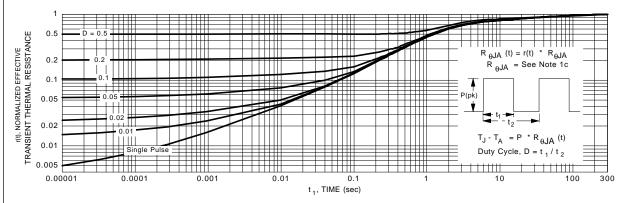


Figure 17. Transient Thermal Response Curve.

Note: Thermal characterization performed using the conditions described in note 1c. Transient thermal response will change depending on the circuit board design.

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